Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP ProDesk 600 G1 Tower Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Yes</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Yes</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Liteon 320W STD</td>
<td>5</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Yes</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>Liteon 320W STD</td>
<td>5</td>
</tr>
<tr>
<td>Components and parts containing toner and ink including liquids, semi-liquids (gel/paste) and toner including chambers, and service stations.</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>#1 Torx Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>#2 Phillips Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>#3 Micro shear</td>
<td>170II</td>
</tr>
</tbody>
</table>

Description #4
Description #5

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel. (see Figure 1 below)
2. Disconnect the cables from the board. (see Figure 2-7 below)
3. Remove the HDD, slim ODD, ODD from cage. (see Figure 8-10 below)
4. Remove the Memory from the board. (see Figure 11 below)
5. Remove the CPU HeatSink from the board. (see Figure 12&13 below)
6. Remove the fan from CPU HeatSink.(see Figure 14&15 below)
7. Remove the CPU from the board. (see Figure 16&17 below)
8. Remove the battery from the system board. (see Figure 18 below)
9. Remove M/B from chassis. (see Figure 19&20 below)
10. Remove system fan from chassis. (see Figure 21&22 below)
11. Remove PSU from chassis. (see Figure 23-25 below)
12. Remove Speaker from chassis. (see Figure 26&27 below)
13. Remove front bezel. (see Figure 28 below)
14. Remove Front I/O and power LED cable. (see Figure 29-31 below)
15. Remove PSU cover. (see Figure 32&33 below)
16. Remove PSU PCA, and disconnect power cables. (see Figure 34&35 below)
17. Remove the Electrolytic Capacitors. (see Figure 36-38 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the access panel
Figure 2 Disconnect PSU cables from the board
Figure 3 Disconnect the ODD/HDD PSU cables
Figure 4 Disconnect the cables from the ODD
Figure 5 Disconnect the cables from the HDD
Figure 6 Disconnect the cooler cable

PSG instructions for this template are available at EL-MF877-01
Figure 7: Disconnect the Front IO cable
Figure 8: Remove the HDD from cage

Figure 9: Remove the slim ODD from cage
Figure 10: Remove the ODD from cage

Figure 11: Remove the Memory from the board
Figure 12: Loose the screws from the CPU HeatSink

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 13 Remove the CPU HeatSink from the board
Figure 14 Loose the screws from the CPU HeatSink

Figure 15 Remove the fan from CPU HeatSink
Figure 16 Rotate the handle and open it up

Figure 17 Remove the CPU from the board
Figure 18 Remove the battery from the system board

PSG instructions for this template are available at EL-MF877-01
Figure 19. Loosen the screws from the board.

Figure 20. Remove M/B from the chassis.

Figure 21. Loosen the screws from the system fan.

Figure 22. Remove the system fan.

Figure 23. Loosen the screws from the PSU.

Figure 24. Press the baffle and slide the PSU.

PSG instructions for this template are available at [EL-MF877-01](#).
Figure 25: Remove PSU from chassis

Figure 26: Loose the screw from Speaker

Figure 27: Remove Speaker

Figure 28: Remove front bezel

Figure 29: Loose the screw of FIO

Figure 30: Remove FIO

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 31 Remove power LED cable

Figure 32 Remove the screws on the PSU chassis

Figure 33 Lift the cover off the power supply

Figure 34 Cut the cable tie

Figure 35 Remove PSU MB from PSU Chassis

Figure 36 Show Ele-Cap on PCBA

(Liteon 320W STD)

PSG instructions for this template are available at [EL-MF877-01](#)
<table>
<thead>
<tr>
<th>Figure37 Remove Ele-Cap from PCBA</th>
<th>Figure38 Remove Ele-Cap from PCBA</th>
</tr>
</thead>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).